

SPUTTERING TARGET ASSEMBLY AND FILM

Abstract

An object of the present disclosure is to provide a tungsten sputtering target assembly with improved peel strength. In one aspect, the present disclosure provides the following invention:

A sputtering target assembly comprising a target, a backing plate, and an insert,

wherein the target consists of W;

the backing plate comprises Ti or a Ti alloy;

the insert comprises Cu or a Cu alloy; and

an average grain size of the target is 20 micrometers or more.